



**AT&S**

# **CONSISTENCY IN** **CHANGE**

**Goldman Sachs - Inaugural Digital Economy Conference**  
Investor and Analyst Presentation

June 17<sup>th</sup>, 2021

# LEADING PROVIDER OF HIGH-END PCBs & IC SUBSTRATES

Well positioned for the future

## Unique market position

- Broad product portfolio to serve all growth markets
- Long-standing customer relationships with technology and market leaders
- Technology innovator due to continuous R&D efforts
- Quality benchmark with outstanding process know-how, productivity and efficiency

## Growth oriented strategy

- Megatrend-driven markets with attractive growth potential
- Address growth opportunities with incremental investments
- Constant outperformance of the PCB & substrates market

€1.2 bn revenue FY 20/21

>€2 bn revenue FY 23/24

# 5

ABF substrates producer worldwide

# 3

in FY 24/25

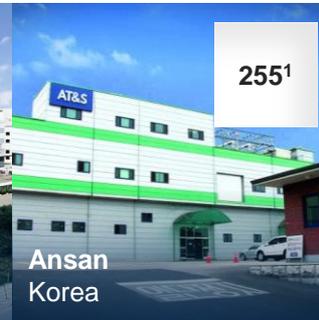
# 2

high-end PCB producer worldwide

ONE

of the leading high-end PCB producers worldwide

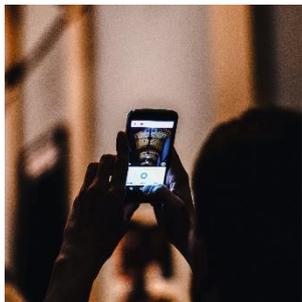
# GLOBAL FOOTPRINT



● AT&S plant    ● AT&S sales support office    📍 AT&S Headquarters

<sup>1</sup> Staff, Average, FTE, FY 20/21; 80 employees in other locations

# MARKET SEGMENTS & PRODUCT APPLICATIONS



**Mobile devices**

- Smartphones
- Wearables
- Notebooks
- Cameras
- Tablets
- SSDs



**IC substrates**

- Data centres
- Microservers
- Client PCs
- Edge computing
- 5G base stations



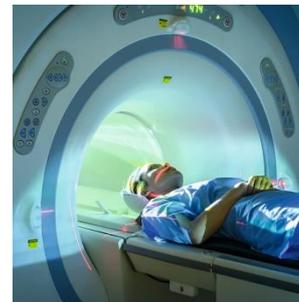
**Automotive**

- ADAS
- Sensoric (radar, lidar, camera, V-to-X communication)
- E-mobility (power supply for motor systems)



**Industrial**

- Smart building, lighting, manufacturing, transportation...
- Telecom infrastructure
- Power management
- Robots & drones



**Medical**

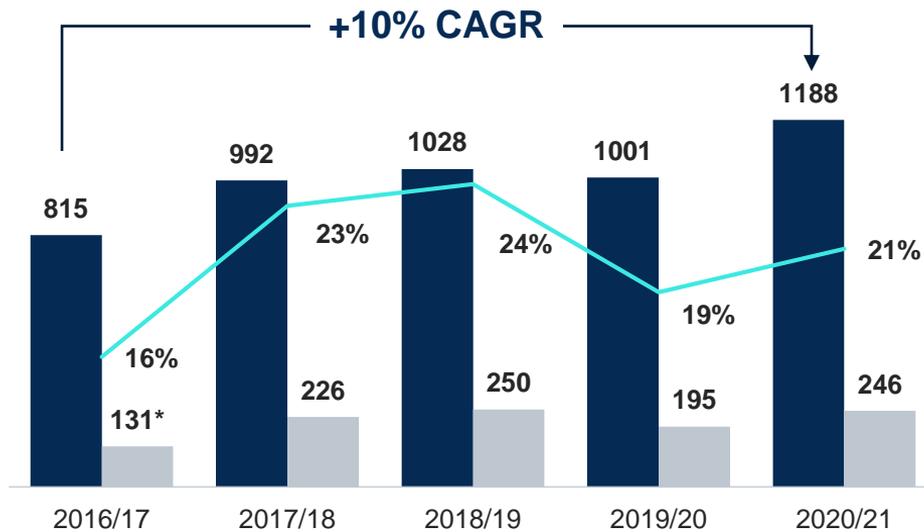
- Diagnostics and imaging systems
- Therapy application (pacemakers, hearing aids, drug delivery ...)
- Patient monitoring

## Segment Mobile Devices & Substrates

## Segment Automotive, Industrial, Medical

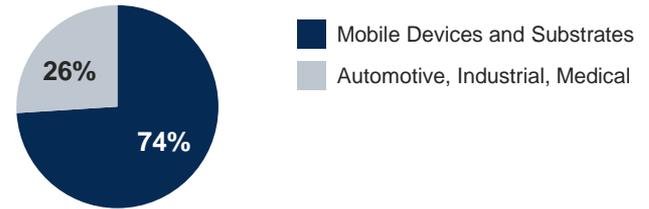
# KEY FACTS

In € mn



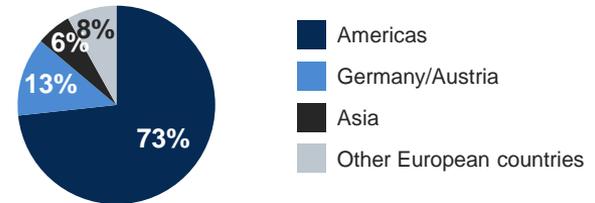
■ Revenue   ■ EBITDA   — EBITDA margin   \* Including ramp-up effects for new plants in China

## Revenue split by segment: FY 20/21



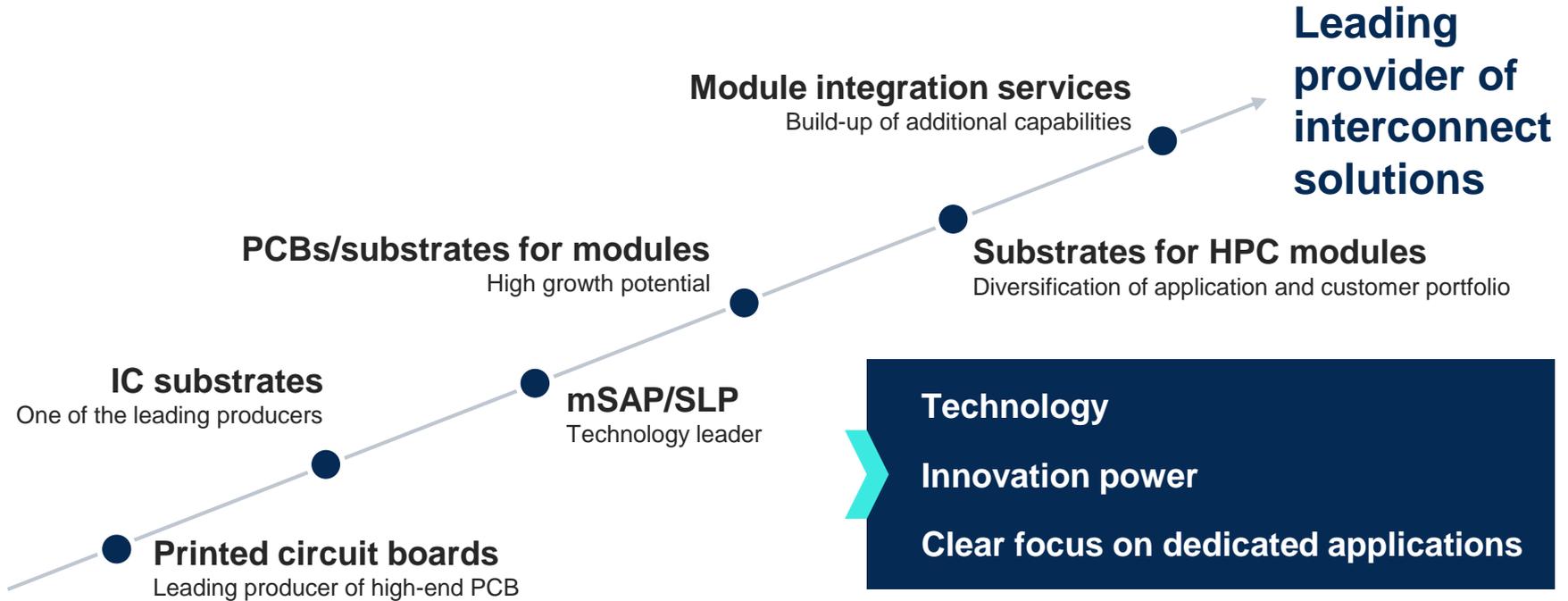
## Revenue split by customer: FY 20/21

Based on customer's headquarters



# “MORE THAN AT&S” - STRATEGY

Broadening the service range and opening up of new business opportunities



# R&D – BASIS FOR TECHNOLOGY LEADERSHIP

**10%**

R&D rate  
(corresponds to  
€ 119 mn)

**R&D**

HQ Austria  
Development up to  
series production at  
the production sites

**429**

Patents

**21%**

Vitality Index\*

International  
R&D partners

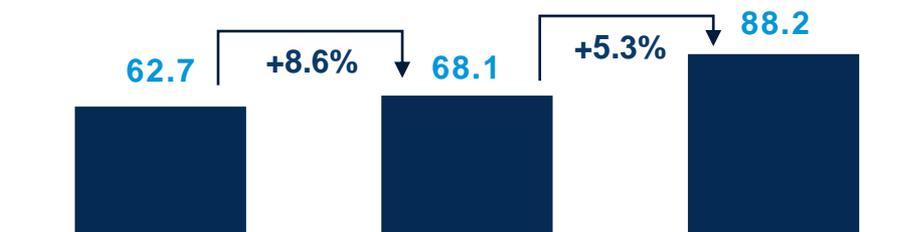


Status: FY 2020/21

\*Share of revenue of technologically innovative products made in the last three years (previously: Innovation Revenue Rate)

# AT&S OUTPERFORMS PCB & IC SUBSTRATES\* MARKET GROWTH

in US\$ bn



	CY 2020	YoY	CY 2021	CAGR	CY 2026
Automotive	6.2	+10.0%	6.8	+6.2%	9.2
Aviation	2.8	+3.9%	2.9	+3.3%	3.4
Industrial	2.5	+5.8%	2.6	+3.8%	3.2
Medical	1.3	+5.0%	1.3	+3.6%	1.6
<b>IC Substrates*</b>	7.7	+23.0%	9.4	+9.1%	14.5
Communication	18.0	+7.3%	19.3	+6.0%	25.8
Computer	16.4	+5.2%	17.3	+3.1%	20.2
Consumer	8.0	+6.9%	8.5	+4.1%	10.4

**+8.6% market growth**  
YoY from 2020 to 2021

**+18.8% AT&S growth**  
YoY in the FY 2020/2021

AT&S will outperform the market with  
an annual growth of  
**20% until 2026**

Source: Prismark 03/2021  
\* only containing high-end IC substrates

# STRATEGIC BUSINESS DRIVERS



# GAME CHANGERS ARE DRIVING OUR BUSINESS

New technologies and systems bring a significant data volume increase



**5G**

**Big Data**

**Artificial Intelligence**

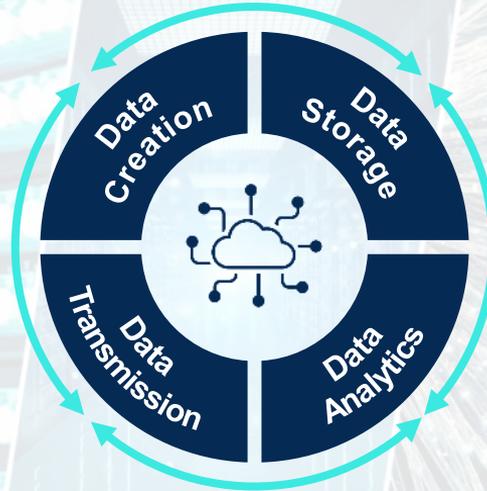
**Internet of Things**

# DIGITALISATION REQUIRES DATA MANAGEMENT

Consumer Electronics | ADAS |  
Industry 4.0 | Medical Applications |  
Internet of Things | ...



Wireless Infrastructure |  
Wireline Infrastructure



HDDs | DRAMs | NANDs



Data Centers | Servers |  
Big Data | In-Memory

**FURTHER  
EXPANSION OF  
IC SUBSTRATES  
BUSINESS**



# ADDITIONAL CAPACITIES FOR IC SUBSTRATES

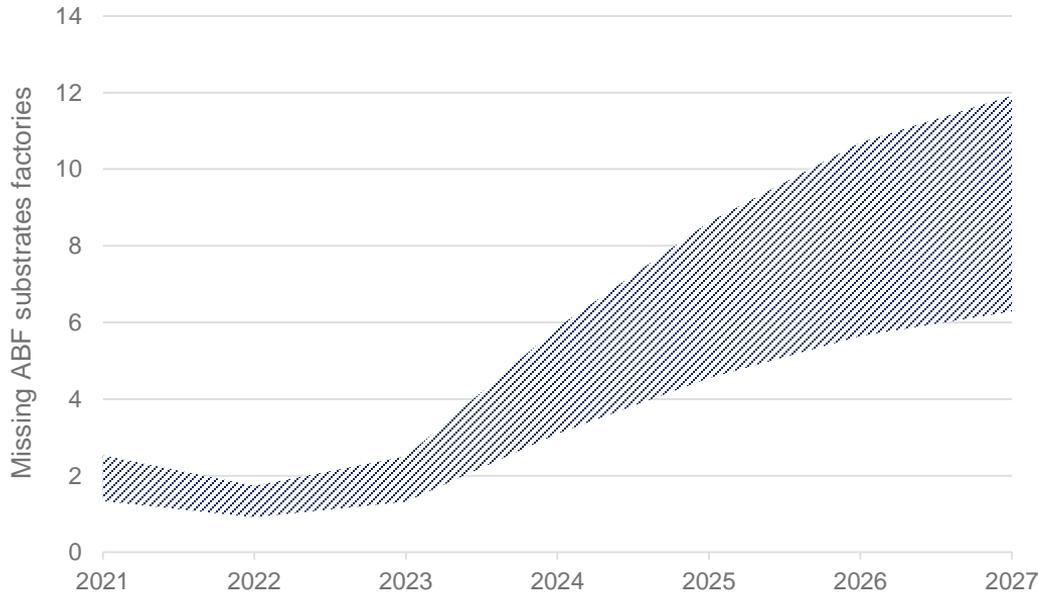
Contracts are expected to be signed in a timely manner

**Future  
diversification  
of the  
customer  
portfolio**

- Investment of up to € 1.7 billion
- Planned production site in Southeast Asia
  - ABF substrates for high-performance processors
  - Construction of new production complex between 2021 - 2026
  - Appr. 200,000 m<sup>2</sup> in size
  - Construction start intended for second half of 2021
  - High volume intended to start at the end of 2024
- Collaboration with two leading manufacturers of high-performance-computing semiconductors
  - Long-term contracts are to be concluded
  - About half of the investment volume is to be provided by the customers' contributions to financing

# CONTINUOUS GROWTH IN ABF SUBSTRATES DEMAND

## Actual gap of required ABF substrates factories to satisfy demand



- Actual gap depends on actual mix in product and technology demand
- Increasing **complexity of high-end** products leads to ongoing strong ABF substrates demand
- Complexity requires **increasing layer count and larger products**
- Current supply shortage is predominantly in high-end products
- Especially **server and AI applications** drive the demand

Source: AT&S Internal assessment  
One factory corresponds to four production lines

# TARGET APPLICATIONS

ABF substrates for  
high-performance  
processors



High-  
performance  
computers &  
data centres

5G & AI  
applications

Gaming

Automotive



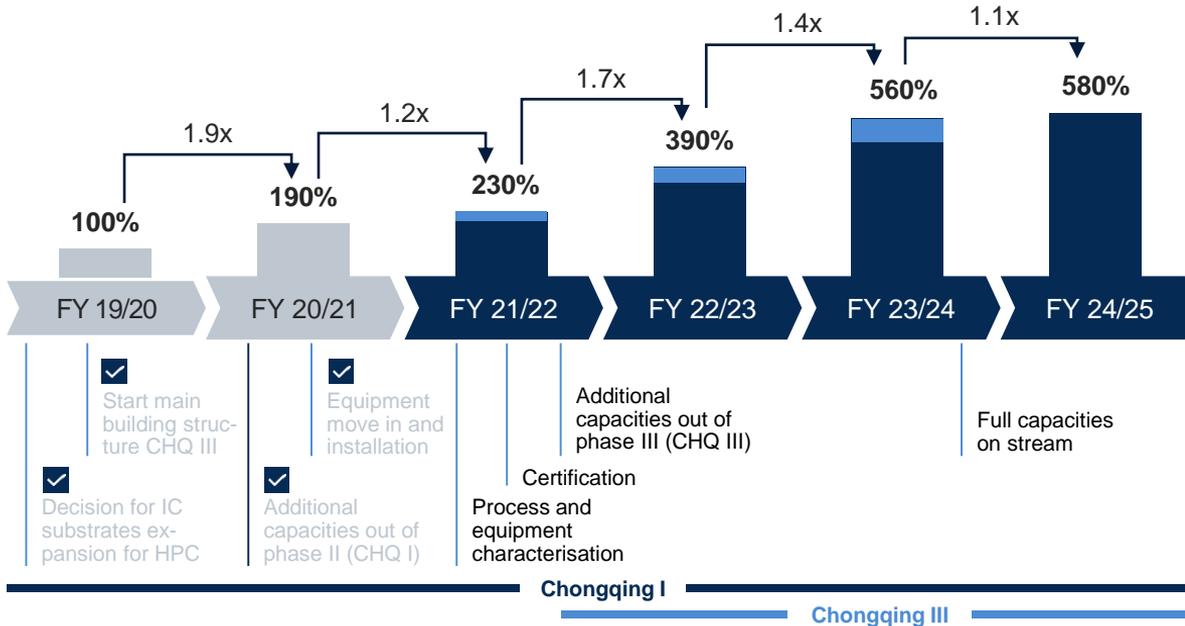
# CAPACITY EXPANSION AT CHONGQING III

On the way to becoming one of the leading high-end ABF substrates producers



# RAMP OF CHONGQING III EARLIER THAN EXPECTED

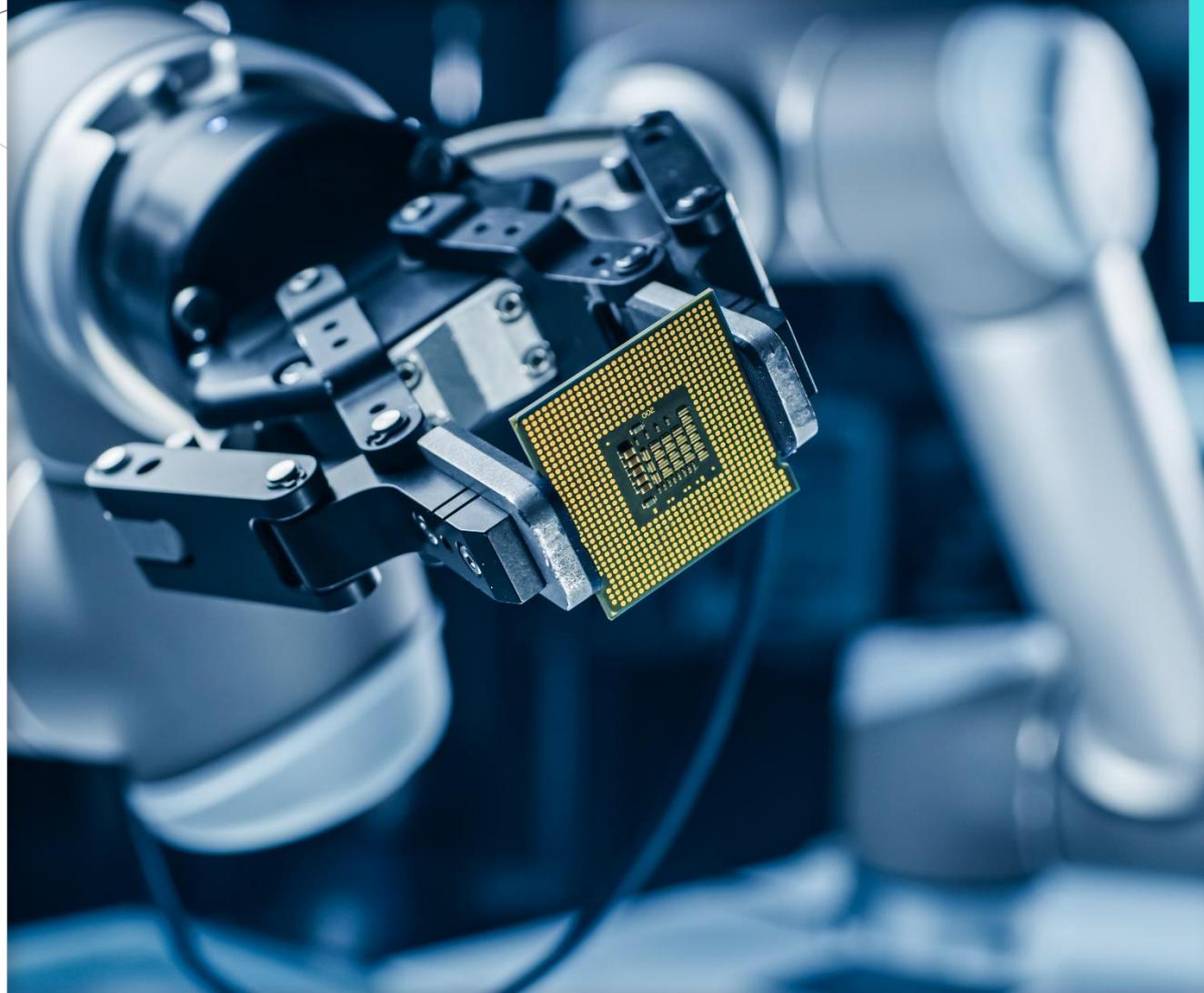
## ABF substrates output capacity



- CHQ III: Production will already be starting in FY 21/22
- Additional € 200 mn investment in CHQ III
- Full capacities available with the beginning of CY 2024 (Q4 23/24)

Additional output capacity due to investment increase and earlier production start in CHQ III

# RESULTS FY 20/21



# KEY DEVELOPMENTS FY 20/21

**Strong full-year results demonstrate AT&S resilience and agility**

**Growing  
profitably  
with served  
markets**

- Additional capacities and strong demand drive ABF substrates business
- Mobile applications supported by customer and application diversification
- PCBs for modules contribute to overall revenue growth
- Automotive with ongoing recovery and Q4 above last year
- Medical & Healthcare with stable performance due to improved demand
- Industrial segment with positive development thanks to better product mix
- Capacity expansion in Chongqing faster than expected

# FY 20/21 RESULTS SUMMARY

## Revenue at historic high

Revenue +19%

**€1,188 mn**

- Negative FX effects of € 37 mn
- +22% at constant fx-rate

EBITDA margin +130 bps

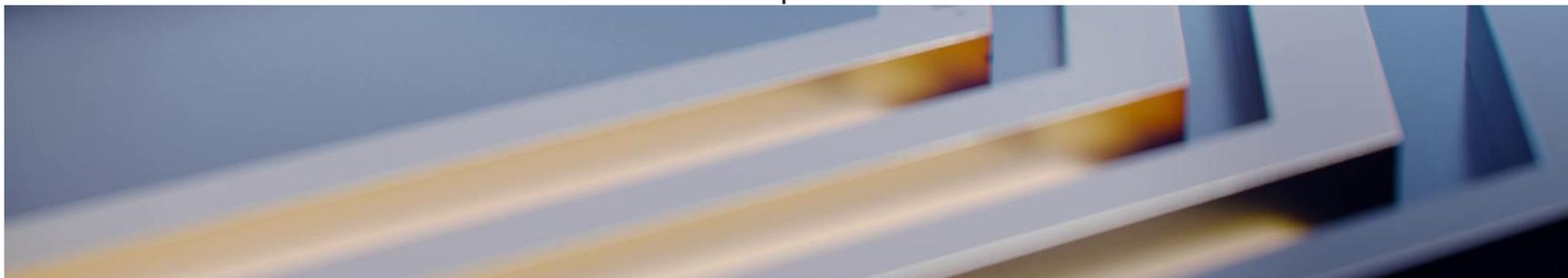
**20.7%**

- Strong EBITDA margin despite headwinds from COVID-19 impacts

ROCE +300 bps

**5.8%**

- Driven by strong operating result



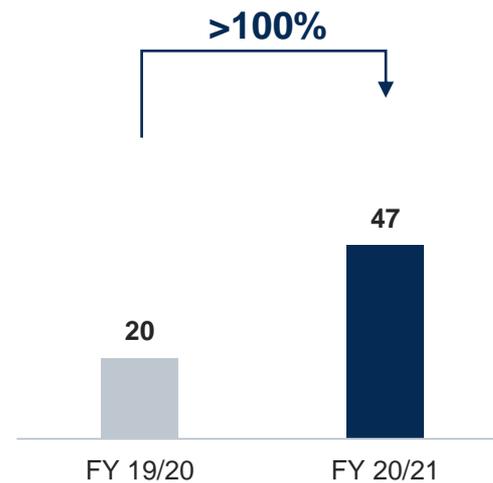
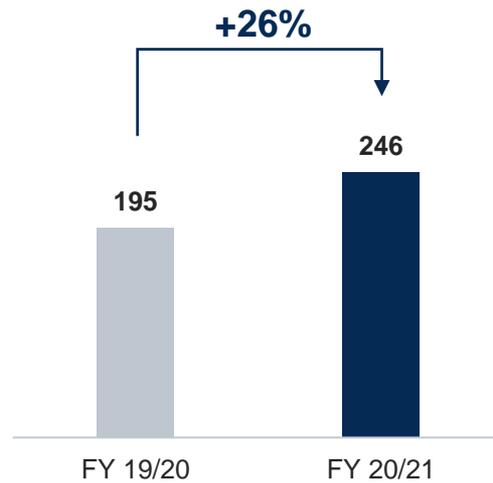
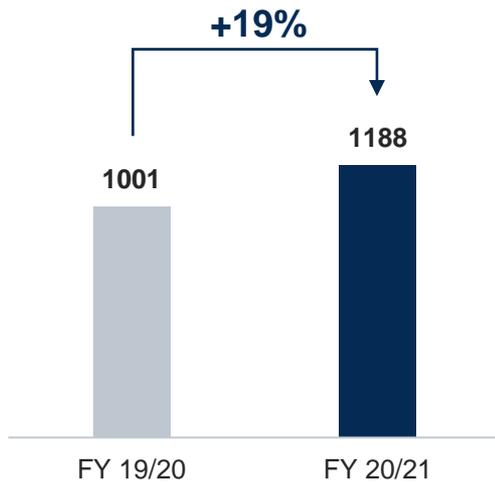
# FY 20/21 RESULTS SUMMARY

## Revenue

## EBITDA

## Net profit

in € mn

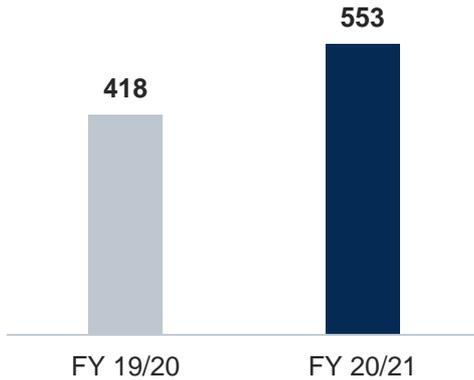


# FY 20/21 FINANCIAL POSITION

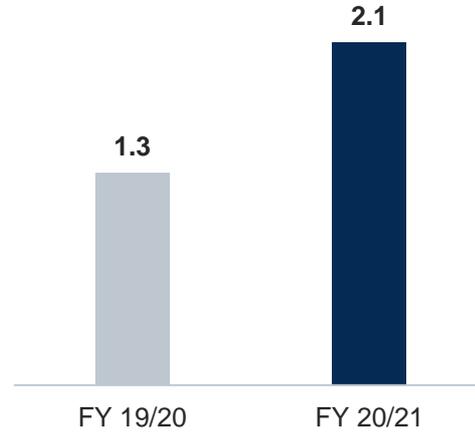
Solid financial structure for future growth

## Cash & cash equivalents

in € mn



## Net debt/EBITDA



## Balancing capital allocation

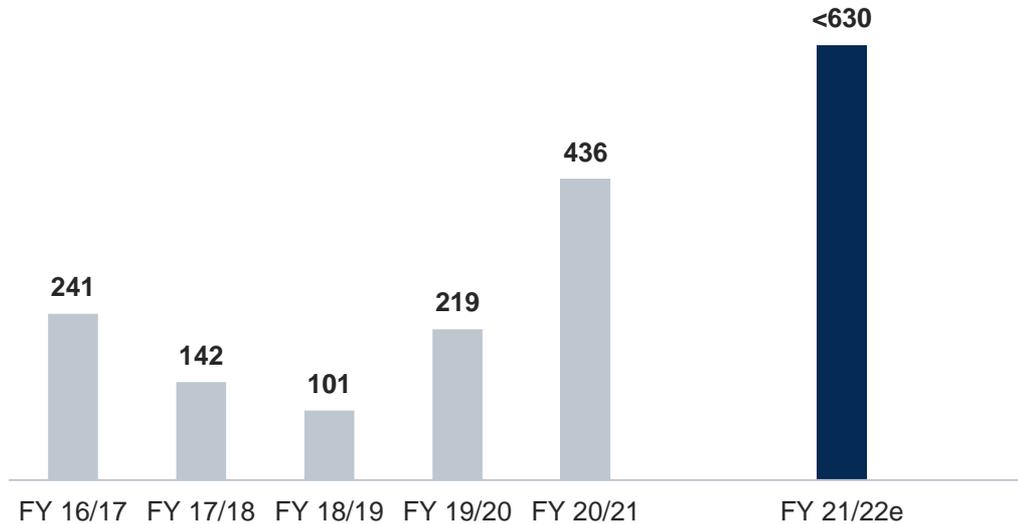
- Deploying capital with clear approach to invest in strategic growth markets
- Increasing net debt level by € 262 m in FY 20/21 due to investments in additional IC substrates capacities

**Sound investment decisions to generate strong operating and free cash flow in the future.**

# NET CAPEX

Investments in IC substrates and module PCBs consistently continued

in € mn



## Capex outlook 2021/22<sup>\*)</sup>

- Depending on market developments CAPEX for maintenance and tech upgrade of up to € 100 m
- CAPEX for strategic projects of up to € 450 m plus € 80 m due to timing variances

<sup>\*)</sup> Does not include investment in SEA

# GUIDANCE FY 21/22

## Further growth ahead

FY 21/22	
<b>Growth</b>	Revenue growth of 13 – 15%
<b>Profitability</b>	Adjusted EBITDA margin of 21 – 23% Adjustment: start-up effects of the Chongqing project with an amount of appr. € 40 mn
<b>CAPEX</b>	<ul style="list-style-type: none"><li>▪ Maintenance and tech-upgrades € 100 mn</li><li>▪ CAPEX from PY (timing variances) € 80 mn</li><li>▪ Expansion projects € 450 m (wo/ new project in SEA)</li></ul>
<b>Dividend proposal</b>	€ 0.39 per share (for FY 20/21)

# GUIDANCE FOR 2025/26

## Considering the investment in Southeast Asia

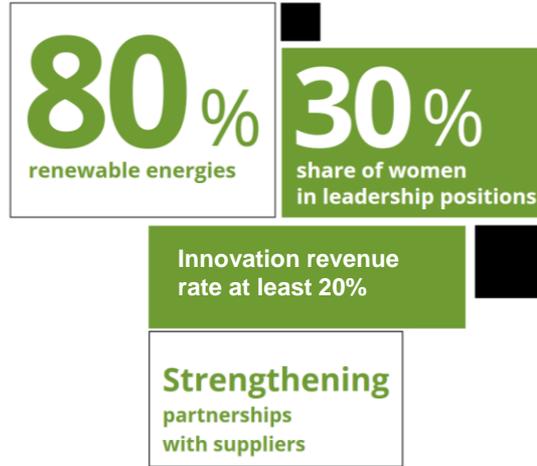
<b>Growth</b>	Revenue appr. € 3 billion (CAGR +20%)
<b>Profitability</b>	<ul style="list-style-type: none"><li>▪ EBITDA margin of 27 – 32%</li><li>▪ ROCE of &gt;12% with ramp-up of production</li></ul>
<b>Others</b>	<p><b>Depending on the balance sheet presentation</b></p> <ul style="list-style-type: none"><li>▪ Net debt / EBITDA could temporarily exceed the medium-term target of &lt;3</li><li>▪ Equity ratio could fall short of the internal target of &gt;30%</li></ul>

# ANNEX



# OUR GREEN DEAL IS DRIVING SUSTAINABILITY

High level of social, ecological and economic responsibility



## Achievements<sup>1</sup>

- Share of renewable energies of 45%<sup>2</sup>
  - Share of women in leadership positions of 20%
  - Innovation revenue rate of 21%
  - 95% of A-suppliers signed our Code of Conduct
- <sup>1</sup> as of 31.03..2021  
<sup>2</sup> including big hydro power

Rated by



# MARKET PLAYERS IN THE HIGH-END SEGMENT

## HDI Technology (2019)

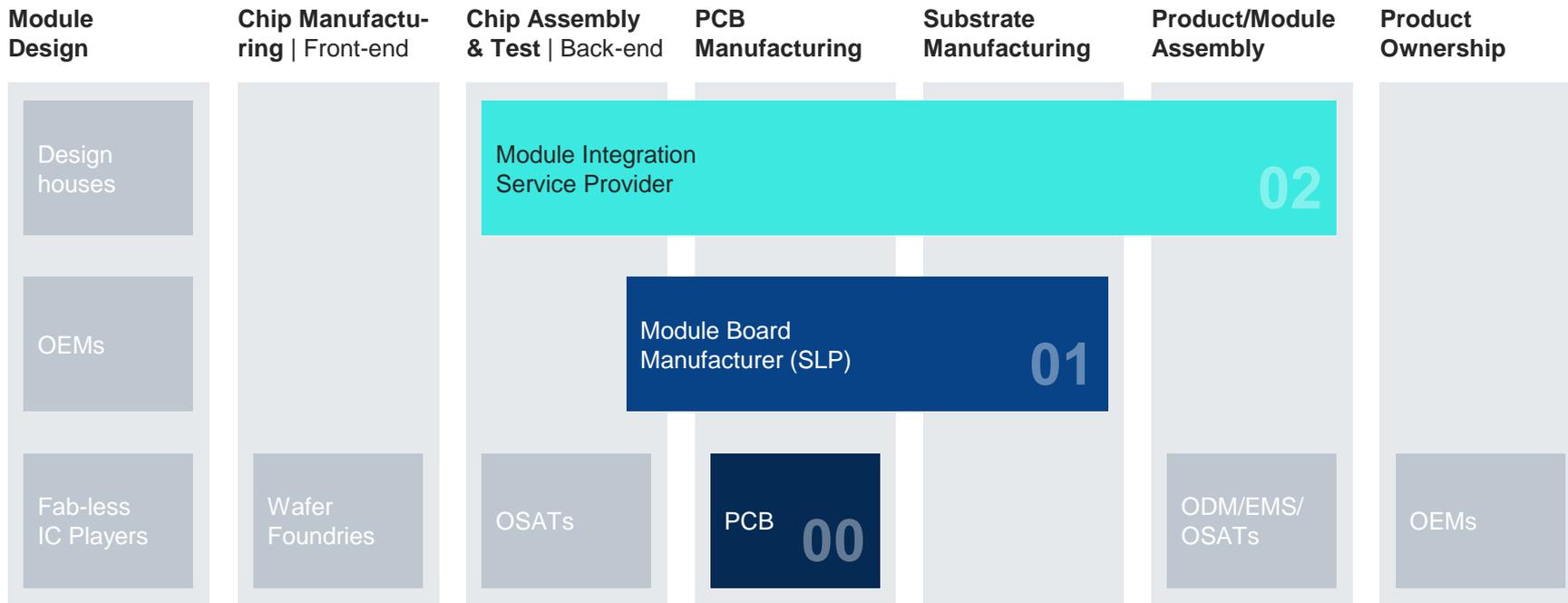
1	Compeq
2	AT&S
3	TTM
4	Unimicron
5	Tripod
6	Meiko
7	Zhen Ding
8	Korea Circuit

## ABF Substrates (2019)

1	Ibiden
2	Unimicron
3	SEMCO
4	Shinko
5	AT&S
6	Kyocera
7	Nan Ya PCB
8	Kinsus

Source: Prismark, JMS, AT&S assessment

# AT&S SOLUTIONS FOR THE ELECTRONICS INDUSTRY



# AT&S – STOCK PROFILE

## Listing

Vienna Stock Exchange,  
Prime Standard

## Indices

ATX, Vönix,  
WBI

## Thomson Reuters (A)

ATSV.VI

## Bloomberg (A)

ATS:AV

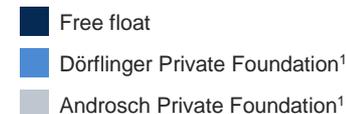
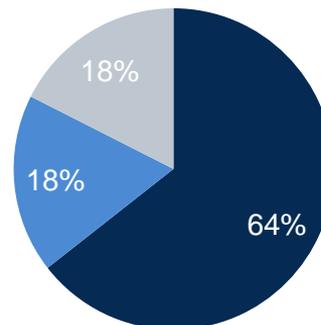
## # of shares outstanding

38.85 m

## Dividend for 20/21

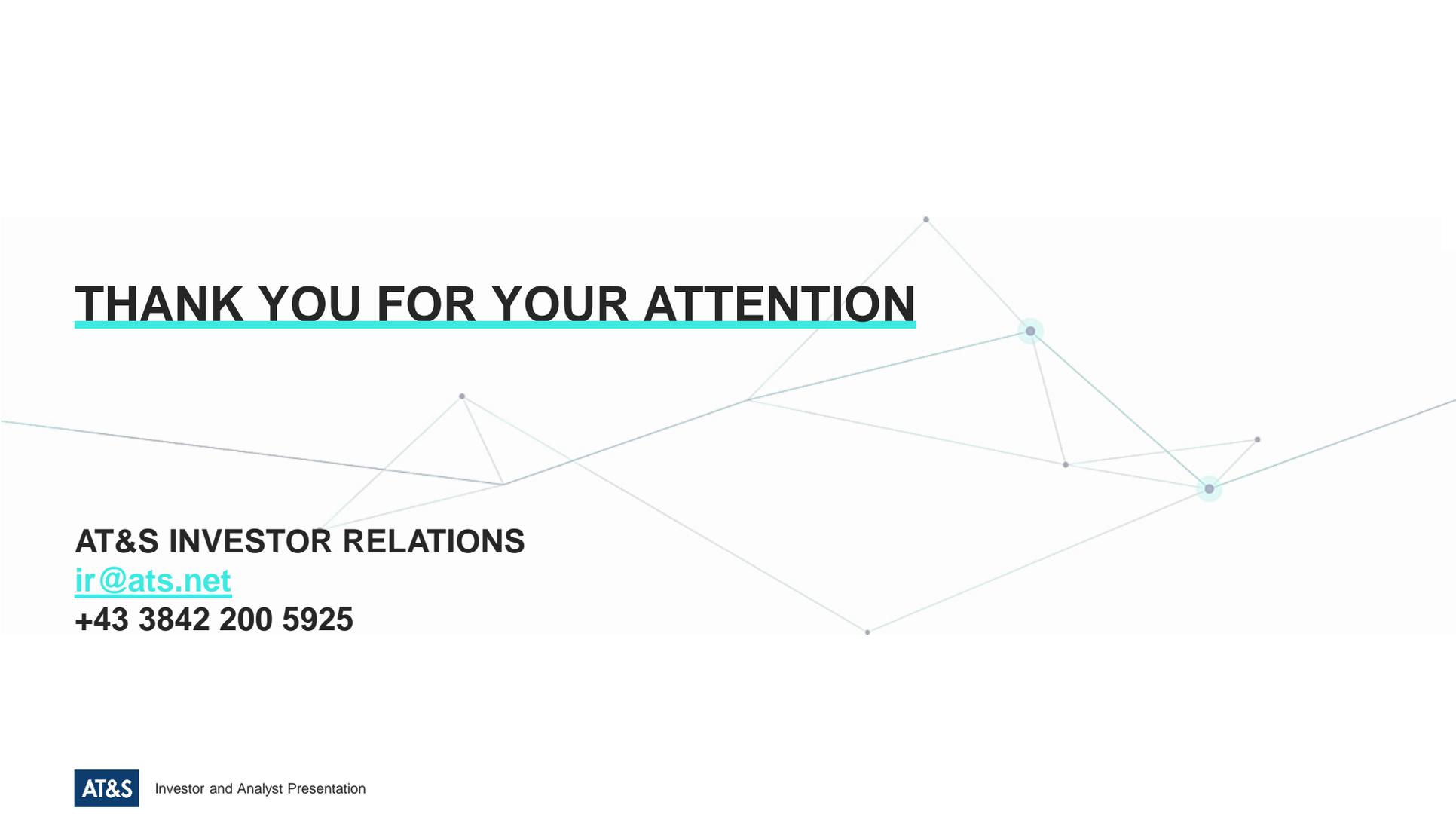
€ 0.39 per share<sup>2</sup>

## Shareholder structure



<sup>1</sup> Including direct and indirect holdings

<sup>2</sup> Proposal to the AGM



**THANK YOU FOR YOUR ATTENTION**

**AT&S INVESTOR RELATIONS**

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